INSTALLATION INSTRUCTIONS - EFFISUS 2BOND DS TAPE

Substrate Preparation

1

All substrates should be dry. Please clean all non-absorptive, smooth substrates, using the Effisus Setup PR Cleaner.

Remove any loose material from absorptive, porous substrates, such as concrete, and sub-coat these substrates with the Effisus Coat EP Primer. Allow the primer to flash off.

Bonding operations cannot be carried out at temperatures below -29ºC. For temperatures between 4.5ºC and -29ºC always sub-coat the substrates with Effisus Coat EP Primer.
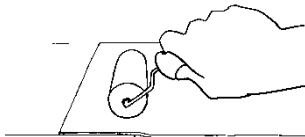
Connecting Operations

2
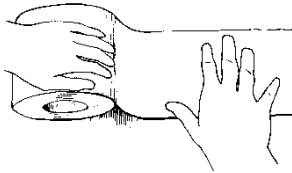
To apply the Effisus 2Bond DS Tape, remove one side of the release liner and apply the tape to the surface which is to be protected or bonded. Rub or roll, with pressure, using your hand or a steel roller, to activate bonding process. Remove the second release liner and adhere the second surface to the tape, applying pressure.
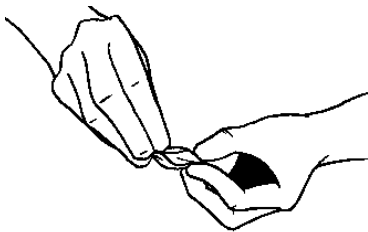
Overlaps

3

Seams between Effisus 2Bond DS Tapes should have a minimum overlap of 100mm.

Adhere the top Effisus 2Bond DS Tape over the bottom Effisus 2Bond DS Tape. Rub or roll with pressure using a steel roller to activate the bonding process.

Putty

4

Effisus 2Bond DS Tape can also be used as a putty. Remove both release liners and roll into a rope. Place Effisus 2Bond DS over the gap and mould it to the seal the opening.

Effisus 2Bond DS Tape is self-sealing. It can be used to seal penetrating screws or nail shanks.